

\*\*\* PCB SPECIFICATION FOR BARE BOARD MANUFACTURING \*\*\*

PRODUCT OWNER : Silicon Labs  
DOCUMENT/BOARD : PCB2010 REV.B02  
DATE : 2013-08-02  
REVISION : B02

PREPARED BY : Ole Jacob Bryhni Frostad  
BOARDS pr PANEL: 4 (1 x 4)  
PANEL SIZE : 126.0 x 260.0 mm  
BOARD SIZE : 110.0 x 55.0 mm  
BOARD THICKNESS: 1.6 mm +/- 10 %  
NO OF LAYERS : 6  
MATERIAL(S) : Glass Epoxy FR-4, IPC-4101 (current revision) /126 or /129  
Td min 340 C (Decomposition Temperature), Tg min 170 C  
CTE, Z-axis max 3.5 % (50 - 260 C)  
Materials in compliance with the RoHS and WEEE directives  
MARKINGS: Logo, Week/Year, UL  
(Avoid areas reserved for DataMatrix, Barcodes or Lables)  
QUALITY REQ. : IPC-A-600 (current revisions) Class 2, and IPC specifications  
referred to by IPC-A-600  
GENERAL REQ. : If applicable, the following requirements are valid:  
- If Build-Up (Stack-Up) is specified, follow Build-Up,  
otherwise use (board manufacturer) standard Build-Up.  
- Copper balancing may be applied on break-away-tabs,  
or otherwise outside board outline(s), but must have  
a minimum 1.5 mm clearance to possible fiducials.  
- Break-away areas may be used for patterns, holes etc  
by manufacturer for QA purposes.  
- If V-CUT use angle 30 +/- 5 degrees.  
V-CUT minimum remaining thickness 0.5 +/- 0.1 mm.  
Use of V-CUT test pads is allowed.  
- Inner radius (contour) 1.2 mm, unless stated otherwise.  
- Manufacturer may plug tented via holes in order to improve yield.  
COPPER THK. : SEE BUILD-UP  
COPPER PASSIV. : ENIG to meet IPC-4552 requirements, except Nickel thickness  
must be minimum 4 um. (Electroless Nickel/Immersion Gold)  
RESIST MASK : Photo Polymer Wet film, BLACK NB!  
to IPC-SM-840 Class T requirements (current revision)  
Thickness minimum 8 um, maximum 20 um  
VIA HOLES : TENTED (OVERPRINTED, NOT PLUGGED) IPC-4761 Type I  
UNLESS OPTIONALLY: EXPLICIT OTHER VIA TREATMENT REQUESTED  
LEGEND COLOUR : WHITE  
LEGEND LAYER(S): BOTH SIDES  
NOMINAL VALUES for Width, Spacing and VIA Diameter:  
Cu TRACK(TRACE): Minimum conductor width : 0.10 mm (4 mils)  
Cu SPACING : Minimum conductor spacing: 0.0889 mm (3.5 mils)  
MINIMUM VIA : Minimum via pad diameter : 0.51 mm (20 mils)  
Min via hole (SEE HOLE INFORMATION FURTHER DOWN)  
Min via hole may have more than one pad diameter.

(SPECIFICATION CONTINUED ON NEXT PAGE)

BUILD UP :

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L1 ===== 35 um Cu (1.0 Oz)
  /////////// C O R E /////////// 100 um
L2 ===== 18 um Cu (0.5 Oz)
  - - - - P R E P R E G - - - - 128 um
L3 ===== 18 um Cu
- - /////////// C O R E /////////// 1000 um - - CENTER - -
L4 ===== 18 um Cu
  - - - - P R E P R E G - - - - 128 um
L5 ===== 18 um Cu
  /////////// C O R E /////////// 100 um
L6 ===== 35 um Cu

```

(Approximate Prepreg thicknesses.)

TEST : 100% Electrical Test  
 Optical test, AOI (with automatic scanner)  
 Visual inspection  
 (Generate netlist from Gerber and Drill files)

Do not use 1080 Prepreg and avoid use of 2125 Prepreg

If NB! is used in this specification, it means:  
 abbreviation for nota bene!, a Latin expression meaning "note well!"

#### NC DRILL - HOLE INFORMATION:

WARNING: Drill dimensions must be taken from the Excellon (.exc) file(s).  
 NON-PLATED holes may have a small center marker in the Gerber files.  
 Under no circumstance must these Gerber flashes be mistaken for the  
 hole drill dimensions!

The drill file may contain slots. See drill information below.  
 The Gerber file mb2010.gex may also contain slot information.  
 Dimensions for the finished board (after plating).  
 Tolerances +/- 0.1 mm, unless specified otherwise below.  
 Via Holes +0.05 mm/-Via Size, unless specified otherwise below.

#### PLATED HOLES:

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T01 VH   DIA = 0.25 mm   QTY = 1980 (VIA-HOLES)
T02 VH   DIA = 0.3 mm    QTY = 1116 (VIA-HOLES)
T03 PTH  DIA = 0.7 mm    QTY = 40
T04 PTH  DIA = 1.0 mm    QTY = 212
T05 PTH  DIA = 3.0 mm    QTY = 4

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#### NON-PLATED HOLES:

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T06 NP   DIA = 0.9 mm    QTY = 8
T07 NP   DIA = 1.6 mm    QTY = 8
T08 NP   DIA = 3.0 mm    QTY = 8

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